

	SPEC	CIFICATION	S
CUSTOMER	:		
SAMPLE CODE	:		
	-	(This Code will be changed wh	nile mass production)
MASS PRODUCT	TION CODE	PC1602LRS-FW (VER.C)	/A-B
	Custome	r Approved	
		Date:	
Sales Sign	QC Confirmed	Checked By	Designer
		Nowlang 3 6/11/2003 JS Tom 6/11/2003	· 不可不可。 6/11/2003
Approval For Specificatio * This specification is sub	ns Only. ject to change without notice		
Please contact Powertip		designing your product based	on this specification.
	Powertip C	Corporation	
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RECORDS OF REVISION

Date	Rev.	Description	Note	Page
2003/05/05	0	Revised Contents		
2003/05/28	А	Update VLCD(MIN.)=(VDD-10.0)V		4
2003/05/31	В	Update Condition IOH=-0.1mA ;IOL=0.1mA; VoH(MAX)= VDD; VoH(MIN)= 3.9V		5
2003/6/11	С	Update: Storage Humidity 20-60%RH → Storage Humidity 90%RH		4

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Note : For detailed information please refer to IC data sheet : <u>ST7066U,KS0065B</u>



1. SPECIFICATIONS

1.1 Features

Item	Standard Value
Display Type	16*2 Characters
LCD Type	STN Gray Positive Transflective Normal Temp.
Driver Condition	LCD Module : 1/16 Duty , 1/4 Bias
Viewing Direction	6 O'clock
Backlight	YG LED B/L
Weight	36.2 g
Interface	-
Other(controller/driver IC)	_

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	84.0 (L)*44.0 (W)*13.7max.(H)	mm
Viewing Area	61.0(L) *15.8(W)	mm
Active Area	56.21(L) *11.5(W)	mm
Dot Size	0.56(L) *0.66(W)	mm
Dot Pitch	0.60(L) *0.70(W)	mm

Note : For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	V _{DD}	_	-0.3	7.0	V
LCD Driver Supply Voltage	V _{LCD}	_	VDD-10.0	VDD+0.3	V
Input Voltage	V _{IN}	_	-0.3	V _{DD} +0.3	V
Operating Temperature	T _{OP}	Excluded B/L	0	50	°C
Storage Temperature	T _{ST}	Excluded B/L	-20	70	°C
Storage Humidity	H _D	Ta<40 °C	-	90	%RH



1.4 DC Electrical Characteristics

	$V_{DD} = 5.0 \text{ V} \pm 10\% \text{ , } V_{SS} = 0 \text{V} \text{ , } Ta = 25 ^{\circ}\text{C}$						
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	
Logic Supply Voltage	V _{DD}	—	4.5	5.0	5.5	V	
"H" Input Voltage	V _{IH}	—	0.7 Vdd	-	VDD	v	
"L" Input Voltage	V _{IL}	_	-0.3	-	0.6	V	
"H" Output Voltage	V _{OH}	IOH=-0.1mA	3.9	-	Vdd	V	
"L" Output Voltage	V _{OL}	IOL=0.1mA	-	-	0.4	V	
Supply Current	I _{DD}	$V_{DD} = 5.0 \text{ V}$	-	1.5	-	mA	
		0°C	-	-	-		
LCM Driver Voltage	V _{OP}	25°C*1	-	4.2	-	v	
		50 °C	-	-	-		

Note: *1. THE V_{OP} TEST POINT IS V_{DD} - V_O .

1.5 Optical Characteristics

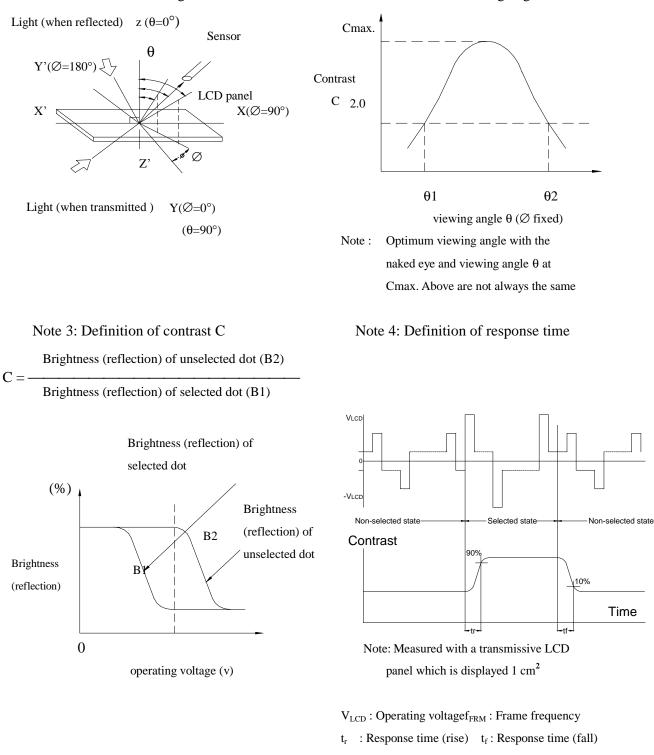
LCD Panel : 1/16 Duty , 1/4 Bias , V_{LCD} =4.2 V , Ta = 25 $^\circ\!\mathrm{C}$

Item	Symbol	Conditions	Min.	Тур.	Max.	Reference
View Angle	θ	C \geq 2.0, Ø = 0°	40°	-	-	Notes 1 & 2
Contrast Ratio	С	$\theta = 5^{\circ}, \ \emptyset = 0^{\circ}$	5	7	-	Note 3
Response Time(rise)	tr	$\theta = 5^{\circ}, \ \emptyset = 0^{\circ}$	-	150 ms	-	Note 4
Response Time(fall)	tf	$\theta = 5^{\circ}, \ \emptyset = 0^{\circ}$	-	300 ms	-	Note 4



Note 1: Definition of angles θ and \emptyset

Note 2: Definition of viewing angles $\theta 1$ and $\theta 2$





1.6 Backlight Characteristics

LCD Module with LED Backlight

Maximum	Ratings
1 iu/illiulli	rungo

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°C	-	300	mA
Reverse Voltage	VR	Ta =25°C	-	8	V
Power Dissipation	РО	Ta =25°C	-	1.38	W
Operating Temperature	T _{OP}	-	-20	70	°C
Storage Temperature	T _{ST}	-	-40	80	°C
Solder Temp. for 3 Second	-	-	-	260	°C

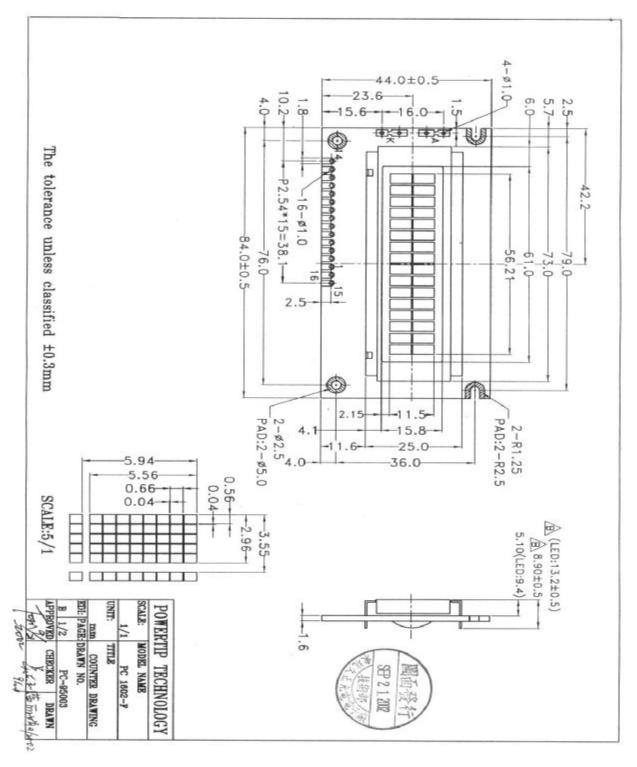
Electrical / Optical Characteristics

					Ta	=25°C
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=120 mA	-	4.2	4.6	V
Reverse Current	IR	VR=8V	-	-	0.2	mA
Wavelength	Hue	IF=120 mA	571	-	576	nm
Luminous Intensity (without LCD)	Iv	IF=120 mA	120	150	-	cd/m ²
Color	Yellow-green					

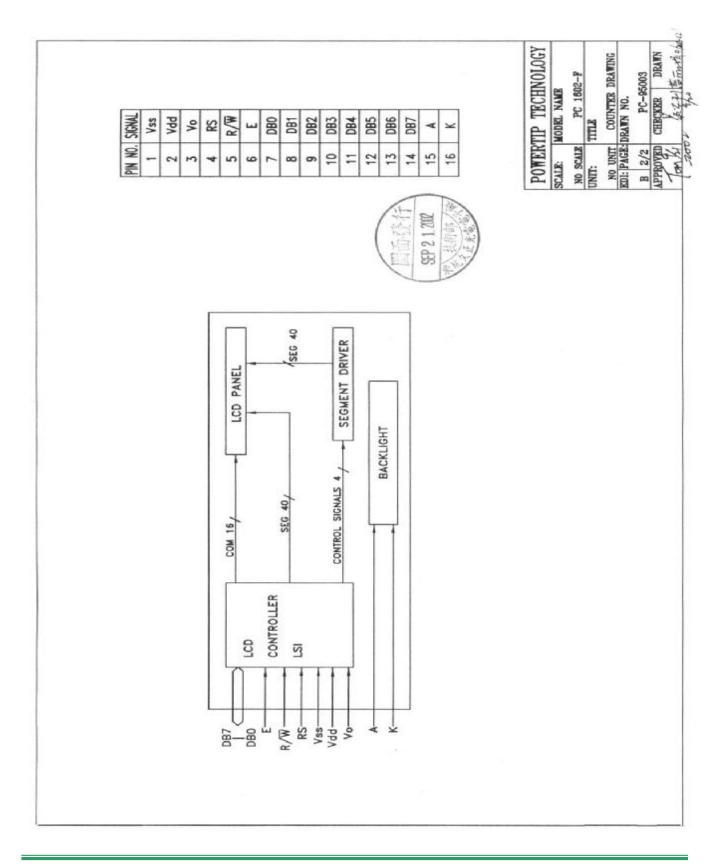


2. MODULE STRUCTURE

2.1 Counter Drawing





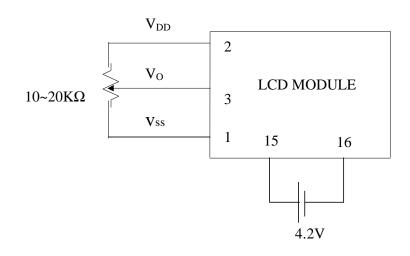




2.2 Interface Pin Description

Pin No.	Symbol	Signal Description
1	V _{SS}	Power Supply (Vss=0)
2	V _{DD}	Power Supply (V _{DD} >V _{SS})
3	Vo	Operating voltage for LCD
		Register Selection input
4	RS	High = Data register
4	KS	Low = Instruction register (for write)
		Busy flag address counter (for read)
		Read/Write signal input is used to select the read/write
5	$\overline{R/W}$	mode
		High = Read mode, Low = Write mode
6	Е	Start enable signal to read or write the data
		Four low order bi-directional three-state data bus lines.
7~10	DB0 ~ DB3	Use for data transfer between the MPU and the LCD
/~10	$DB0 \sim DB3$	module.
		These four are not used during 4-bit operation.
		Four high order bi-directional three-state data bus lines.
11~14	DB4 ~ DB7	Used for data transfer between the MPU and the LCD
11~14	$DD4 \sim DD7$	module.
		DB7 can be used as a busy flag.
15	А	Power supply for LED B / L (+)
16	K	Power supply for LED B / L (-)

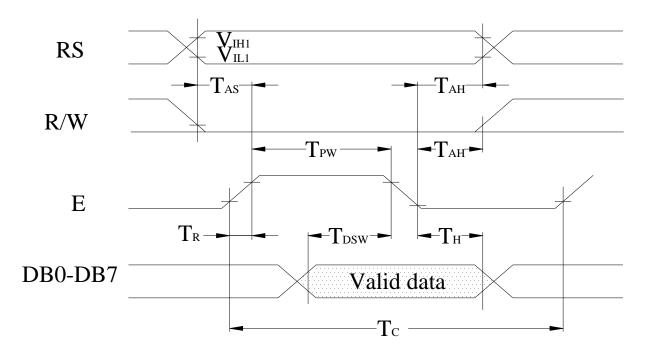
Contrast Adjust



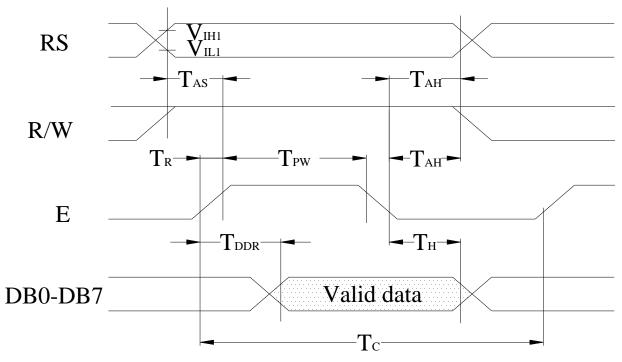


2.3 Timing Characteristics

• Writing data from MPU to ST7066U



I Reading data from ST7066U to MPU





• Write Mode (Writing data from MPU to ST7066U)

 $(Vcc = +5V, Ta = 25^{\circ}C)$

Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
T _C	Enable Cycle Time	Pin E	1200	-	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T _{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T _{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T _{DSW}	Data Setup Time	Pins:DB0~DB7	40	-	-	ns
T _H	Data Hold Time	Pins:DB0~DB7	10	-	-	ns

• Read Mode (Reading data from ST7066U to MPU)

 $(Vcc = +5V, Ta = 25^{\circ}C)$

Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
T _C	Enable Cycle Time	Pin E	1200	-	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T _{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T _{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T _{DDR}	Data Setup Time	Pins:DB0~DB7	-	-	100	ns
T _H	Data Hold Time	Pins:DB0~DB7	10	-	-	ns



2.4 Display Command

	Instruction Code									Description		
Instructions	RS	RS R/W		DB 6	DB 5	DB 4	DB 3	DB 2	DB DB 1 0		Description	Time (270KHz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC.	1.52ms
Return Home	0	0	0	0	0	0	0	0	1	×	Set DDRAM address to "00H" from AC and return cursor to it's original position if shifted. The contents of DDRAM are not changed.	1.52ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	S	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37us
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D=1 : entire display on C=1 : cursor on B=1 : cursor position on	37µs
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	x	×	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	37µs
Function Set	0	0	0	0	1	DL	N	F	×	×	DL: interface data is 8/4 bits NL: number of line is 2/1 F: font size is 5×11/5×8	37µs
Set CGRAM Address	0	0	0	1	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Set CGRAM address in address counter.	37µs
Set DDRAM Address	0	0	1	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Set DDRAM address in address counter.	37µs



Read Busy Flag and Address	0	1	BF	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0µs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	37µs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	37µs

Note:

Be sure the ST7066U is not in the busy state (BF=0) before sending an instruction from the MPU to the ST7066.

If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself.

Refer to Instruction Table for the list of each instruction execution time .

POWERTIP

2.5 Character Pattern

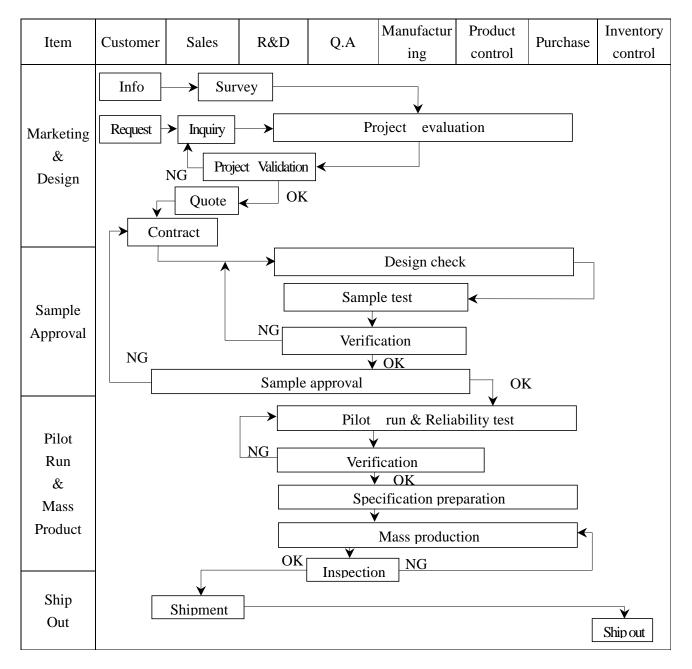
Lower 4 Bits	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
xxxx0000	CG RAM (1)			Ø	30	[•••						-57	₩.	œ	j:
xxxx0001	(2)		:	1			-===	·::::				<u> </u>		ć.,		
xxxx0010	(3)		::	2		R	Ŀ⊃	ŀ			1	-:	•	'	jii:	0
xxxx0011	(4)		#			<u></u>	€	<u>.</u>				-		1	::::-	
xxxx0100	(5)		\$::].	D	Τ		t .			·		ŀ.		[]	53
xxxx0101	(6)						::::•	II				7	;)		::::	ü
xxxx0110	(7)		8.	e,		IJ	÷	ц.)				<u>_</u>			p	2
xxxx0111	(8)		3	7	G	IJ	-	I.I.I				-	32		9	31
xxxx1000	(1)		¢	8	ŀ	24	ŀ'n)×:				-77	:4:	IJ	.,I ^{rr}	30
xxxx1001	(2))	9	Ι		i	•!			-:::	- ' ']'	1	11.	:	<u></u>
xxxx1010	(3)		:-[-:			2	.ji						1	L	Ĵ.	-
xxxx1011	(4)		[;;	k:	Ľ	k	-{			:#F	ÿ	l		:-:	
xxxx1100	(5)		;•		.	4	1				1::-			· _]	÷	P
xxxx1101	(6)		•••••		ŀ·1]]	[*]	3					···.		ŧ	<u>:</u>
xxxx1110	(7)			>	ŀ··l		F~1	j-				12	:1:	•••	P	
xxxx1111	(8)			?				-÷		1	• : .•	1			÷	

CHARACTER PATTERN(SO/HO/EA,WA)

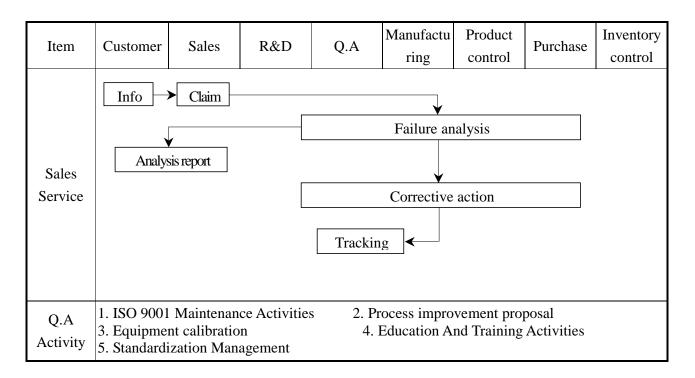


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart









3.2 Inspection Specification

Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level II • Equipment : Gauge • MIL-STD • Powertip Tester • Sample •

IQC Defect Level : Major Defect AQL 0.4; Minor Defect AQL 1.5 $\,\circ\,$

FQC Defect Level : 100% Inspection •

OUT Going Defect Level : Sampling $\,^\circ$

Specification :

NO	Item	Specification	Judge	Level
1	Part Number	The part number is inconsistent with work order of production	N.G.	Major
2	Quantity	The quantity is inconsistent with work order of production	N.G.	Major
	Electronic	The display lacks of some patterns.	N.G.	Major
	characteristics of	Missing line.	N.G.	Major
3	LCM	The size of missing dot, A is $> 1/2$ Dot size	N.G.	Major
	$A=(L+W)\div 2$	There is no function.	N.G.	Major
		Output data is error	N.G.	Major
		Material is different with work order of production	N.G.	Major
		LCD is assembled in inverse direction	N.G.	Major
		Bezel is assembled in inverse direction	N.G.	Major
		Shadow is within LCD viewing area + 0.5 mm	N.G.	Major
	Appearance of	The diameter of dirty particle, A is $>$ 0.4 mm	N.G.	Minor
	LCD A=(L+W)÷2 Dirty particle (Including scratch \ bubble)	Dirty particle length is $>$ 3.0mm, and 0.01mm $<$ width \leq 0.05mm	N.G.	Minor
4		Display is without protective film	N.G.	Minor
		Conductive rubber is over bezel 1mm	N.G.	Minor
		Polarizer exceeds over viewing area of LCD	N.G.	Minor
		Area of bubble in polarizer, $A > 1.0$ mm, the number of bubble is > 1 piece.	N.G.	Minor
		0.4mm $<$ Area of bubble in polarizer, A < 1.0 mm, the number of bubble is >4 pieces.	N.G.	Minor
		Burned area or wrong part number is on PCB	N.G.	Major
		The symbol, character, and mark of PCB are unidentifiable.	N.G	Minor
		The stripped solder mask , A is > 1.0mm	N.G.	Minor
	Appearance of	0.3 mm < stripped solder mask or visible circuit, A < 1.0mm, and the number is ≥ 4 pieces	N.G.	Minor
5	PCB	There is particle between the circuits in solder mask	N.G	Minor
	$A=(L+W)\div 2$	The circuit is peeled off or cracked	N.G	Minor
		There is any circuits risen or exposed.	N.G	Minor
		$0.2 \text{mm} < \text{Area of solder ball, A is } \leq 0.4 \text{mm}$ The number of solder ball is ≥ 3 pieces	N.G	Minor
		The magnitude of solder ball, A is >0.4 mm.	N.G	Minor



NO	Item	Specification	Judge	Level
		The shape of modeling is deformed by touching.	N.G.	Major
	Appearance of	Insufficient epoxy: Circuit or pad of IC is visible	N.G.	Minor
6	molding A=(L+W)÷2	Excessive epoxy: Diameter of modeling is >20 mm or height is >2.5 mm	N.G.	Minor
		The diameter of pinhole in modeling, A is >0.2 mm.	N.G.	Minor
		The folding angle of frame must be $>45^{\circ} +10^{\circ}$	N.G.	Minor
7	Appearance of frame	The area of stripped electroplate in top-view of frame, A is >1.0 mm.	N.G.	Minor
7	$A=(L+W)\div 2$	Rust or crack is (Top view only)	N.G.	Minor
		The scratched width of frame is >0.06mm. (Top view only)	N.G.	Minor
	Electrical	The color of backlight is nonconforming	N.G.	Major
	Electrical	Backlight can't work normally.	N.G.	Major
8	characteristic of backlight	The LED lamp can't work normally	N.G.	Major
0	$A=(L+W)\div 2$	The unsoldering area of pin for backlight, A is $> 1/2$ solder joint area.	N.G.	Minor
	$A = (L + W) \cdot 2$	The height of solder pin for backlight is >2.0 mm	N.G.	Minor
		The mark or polarity of component is unidentifiable.	N.G.	Minor
		The height between bottom of component and surface of the PCB is floating >0.7 mm	N.G.	Minor
10	Assembly parts A=(L+W)÷2	D > 1/4W W $D\downarrow \downarrow \downarrow\downarrow \downarrow \downarrow\downarrow \downarrow \downarrow\downarrow \downarrow \downarrow\downarrow \downarrow \downarrow\downarrow \downarrow \downarrow\downarrow \downarrow \downarrow \downarrow\downarrow \downarrow \downarrow \downarrow \downarrow\downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow \downarrow$	N.G.	Minor
		End solder joint width, D' is $>50\%$ width of component termination or width of pad	N.G.	Minor
		Side overhang, D is $>25\%$ width of component termination.	N.G.	Minor
		Component is cracked, deformed, and burned, etc.	N.G.	Minor
		The polarity of component is placed in inverse direction.	N.G.	Minor
		Maximum fillet height of solder extends onto the component body or minimum fillet height is <0.5 mm.	N.G.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

NO	Item	Test Co	ondition					
1	High Temperature Storage	Storage at 80 $\pm 2^{\circ}$ C 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs						
2	Low Temperature Storage	Storage at -30 $\pm 2^{\circ}$ C 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs						
3	High Temperature /Humidity Storage	 1.Storage 96~100 hrs 60±2°C, 90~ temperature, then storage at nor (Excluding the polarizer). or 2.Storage 96~100 hrs 40±2°C, 90~ temperature, then storage at nor 	rmal condition 4hrs. -95%RH surrounding rmal condition 4 hrs.					
4	Temperature Cycling	$-20^{\circ}C \rightarrow 25^{\circ}C \rightarrow 70^{\circ}C \rightarrow 25^{\circ}C$ $(30\text{mins}) (5\text{mins}) (30\text{mins}) (5\text{mins})$ 10 Cycle						
5	Vibration	10~55Hz (1 minute) 1.5mm X,Y and Z direction * (each 2hrs)						
6	ESD Test	Air Discharge: Apply 6 KV with 5 times discharge for each polarity +/- Testing location: Around the face of LCD	Contact Discharge: Apply 250V with 5 times discharge for each polarity +/- Testing location: 1.Apply to bezel. 2.Apply to Vdd, Vss.					
7	Drop Test	Packing Weight (Kg) 0 ~ 45.4 45.4 ~ 90.8 90.8 ~ 454 Over 454	Drop Height (cm) 122 76 61 46					

5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks , be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands , this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $280\pm10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM .

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is $25^{\circ}C \pm 5^{\circ}C$ and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.